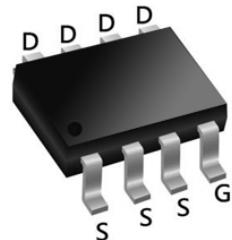


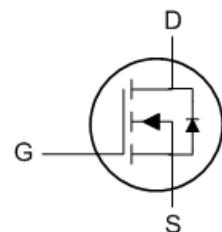
## N-Ch 100V Fast Switching MOSFETs

### Features:

- ★ 100% EAS Guaranteed
- ★ Low  $R_{DS(ON)}$
- ★ Low Gate Charge
- ★ RoHS and Halogen-Free Compliant



### SOP8 Pin Configuration



### Product Summary

| BVDSS | RDSON | ID    |
|-------|-------|-------|
| 100V  | 12mΩ  | 11.5A |

### Absolute Maximum Ratings

| Symbol                 | Parameter                                  | Rating     | Units |
|------------------------|--|------------|-------|
| $V_{DS}$               | Drain-Source Voltage                       | 100        | V     |
| $V_{GS}$               | Gate-Source Voltage                        | $\pm 20$   | V     |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current <sup>1</sup>      | 11.5       | A     |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current <sup>1</sup>      | 9          | A     |
| $I_{DM}$               | Pulsed Drain Current <sup>2</sup>          | 46         | A     |
| EAS                    | Single Pulse Avalanche Energy <sup>3</sup> | 12         | mJ    |
| $I_{AS}$               | Avalanche Current                          | 9          | A     |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation <sup>4</sup>       | 3.1        | W     |
| $T_{STG}$              | Storage Temperature Range                  | -55 to 150 | °C    |
| $T_J$                  | Operating Junction Temperature Range       | -55 to 150 | °C    |

### Thermal Data

| Symbol          | Parameter   | Typ. | Max. | Unit |
|-----------------|---|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10s$ ) | ---  | 40   | °C/W |
|                 | Thermal Resistance Junction-Ambient <sup>1</sup>                  | ---  | 75   | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>                     | ---  | 24   | °C/W |

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

| Symbol                   | Parameter                                      | Conditions   | Min | Typ | Max   | Unit             |
|--------------------------|--|--|-----|-----|-------|------------------|
| $\text{BV}_{\text{DSS}}$ | Drain-Source Breakdown Voltage                 | $V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$  | 100 | --- | ---   | V                |
| $R_{\text{DS(ON)}}$      | Static Drain-Source On-Resistance <sup>2</sup> | $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=11.5\text{A}$   | --- | 9   | 12    | $\text{m}\Omega$ |
|                          | Static Drain-Source On-Resistance <sup>2</sup> | $V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=9.5\text{A}$   | --- | 12  | 15.   |                  |
| $V_{\text{GS(th)}}$      | Gate Threshold Voltage                         | $V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=250\mu\text{A}$  | 1.2 | --- | 2.3   | V                |
| $I_{\text{DSS}}$         | Drain-Source Leakage Current                   | $V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$                              | --- | --- | 1     | $\text{uA}$      |
|                          |  | $V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^{\circ}\text{C}$                              | --- | --- | 5     |                  |
| $I_{\text{GSS}}$         | Gate-Source Leakage Current                    | $V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$   | --- | --- | $\pm$ | nA               |
| $g_{\text{fs}}$          | Forward Transconductance                       | $V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=11.5\text{A}$  | --- | 45  | ---   | S                |
| $Q_{\text{g}}$           | Total Gate Charge (10V)                        | $V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=11.5\text{A}$                          | --- | 35  | ---   | nC               |
| $Q_{\text{g}}$           | Total Gate Charge (4.5V)                       |  | --- | 16  | ---   |                  |
| $Q_{\text{gs}}$          | Gate-Source Charge                             |  | --- | 8   | ---   |                  |
| $Q_{\text{gd}}$          | Gate-Drain Charge                              |  | --- | 4   | ---   |                  |
| $T_{\text{d(on)}}$       | Turn-On Delay Time                             | $V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=3\Omega$ , $I_{\text{D}}=11.5\text{A}$ | --- | 9   | ---   | ns               |
| $T_{\text{r}}$           | Rise Time                                      |  | --- | 4.5 | ---   |                  |
| $T_{\text{d(off)}}$      | Turn-Off Delay Time                            |  | --- | 35  | ---   |                  |
| $T_{\text{f}}$           | Fall Time                                      |  | --- | 5.5 | ---   |                  |
| $C_{\text{iss}}$         | Input Capacitance                              | $V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$                                       | --- | 255 | ---   | pF               |
| $C_{\text{oss}}$         | Output Capacitance                             |  | --- | 305 | ---   |                  |
| $C_{\text{rss}}$         | Reverse Transfer Capacitance                   |  | --- | 12  | ---   |                  |

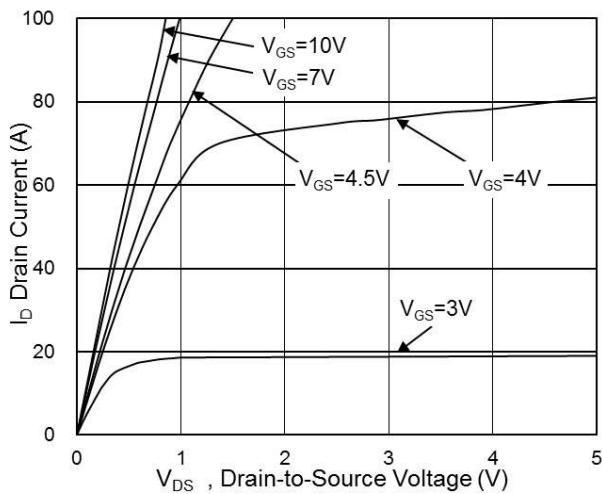
**Diode Characteristics**

| Symbol          | Parameter                                | Conditions   | Min | Typ | Max | Unit |
|-----------------|--|--|-----|-----|-----|------|
| $I_{\text{s}}$  | Continuous Source Current <sup>1,5</sup> | $V_{\text{G}}=V_{\text{D}}=0\text{V}$ , Force Current                                    | --- | --- | 4   | A    |
| $V_{\text{SD}}$ | Diode Forward Voltage <sup>2</sup>       | $V_{\text{GS}}=0\text{V}$ , $I_{\text{s}}=1\text{A}$ , $T_J=25^{\circ}\text{C}$          | --- | --- | 1.1 | V    |
| $t_{\text{rr}}$ | Reverse Recovery Time                    | $I_{\text{F}}=11.5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^{\circ}\text{C}$ | --- | 28  | --- | nS   |
|                 | Reverse Recovery Charge                  |  | --- | 120 | --- | nC   |

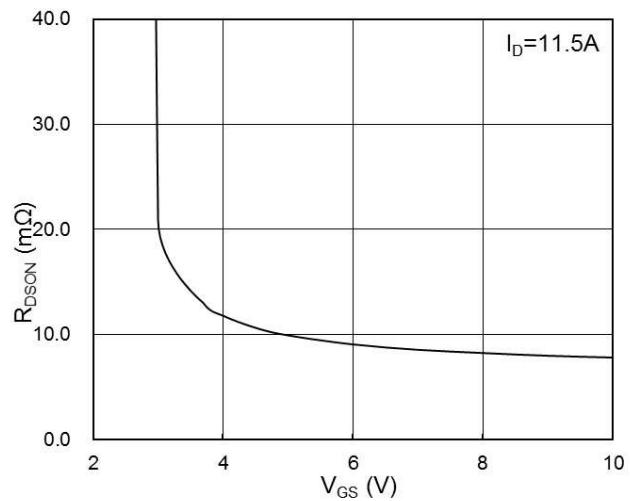
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.3\text{mH}$ ,  $I_{\text{AS}}=9\text{A}$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

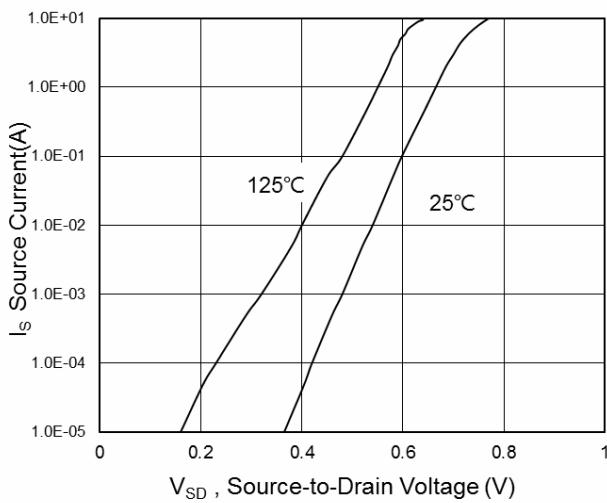
### Typical Characteristics



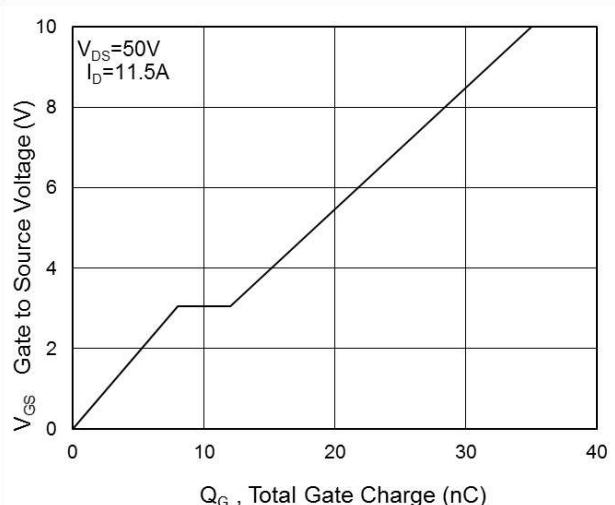
**Fig.1 Typical Output Characteristics**



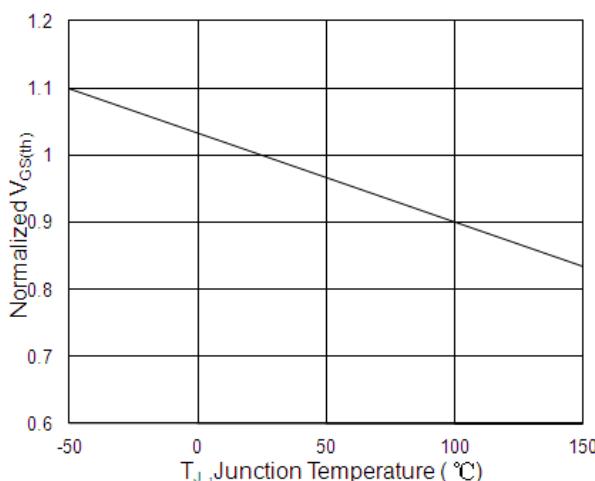
**Fig.2 On-Resistance vs. G-S Voltage**



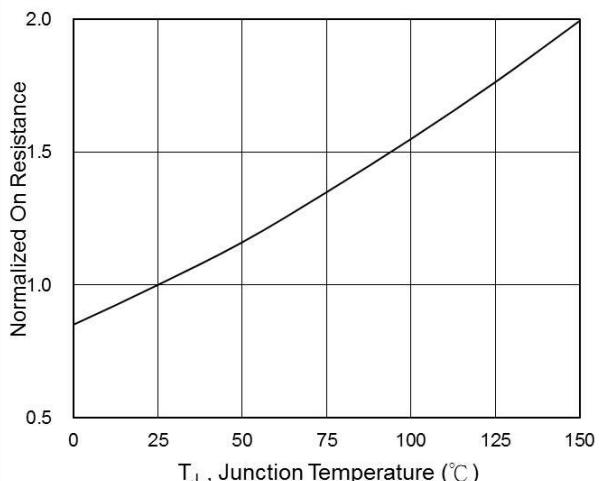
**Fig.3 Source-Drain Forward Characteristics**



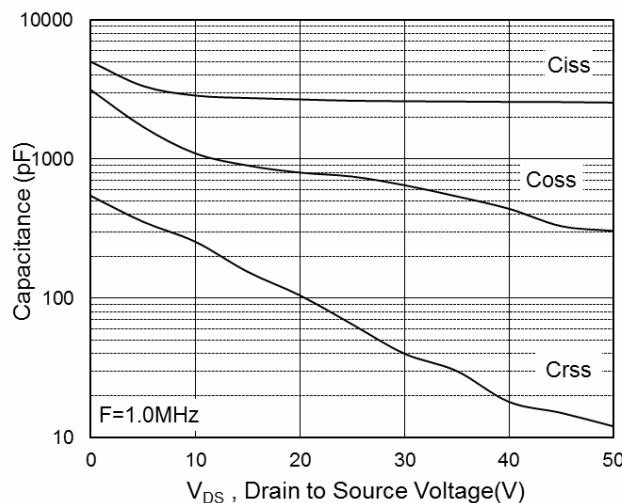
**Fig.4 Gate-Charge Characteristics**



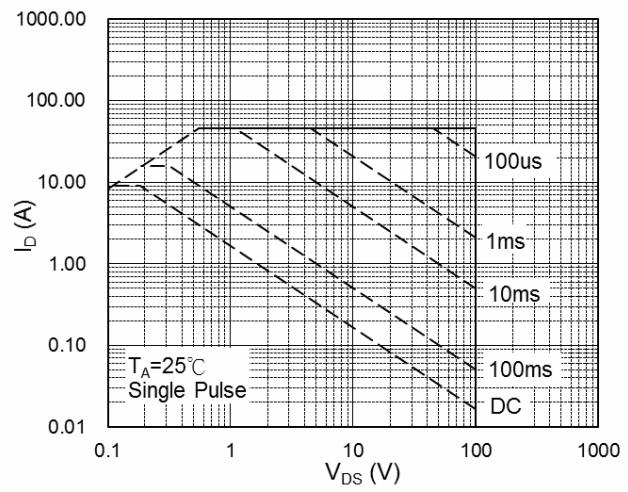
**Fig.5 Normalized V<sub>G</sub>(th) vs. T<sub>J</sub>**



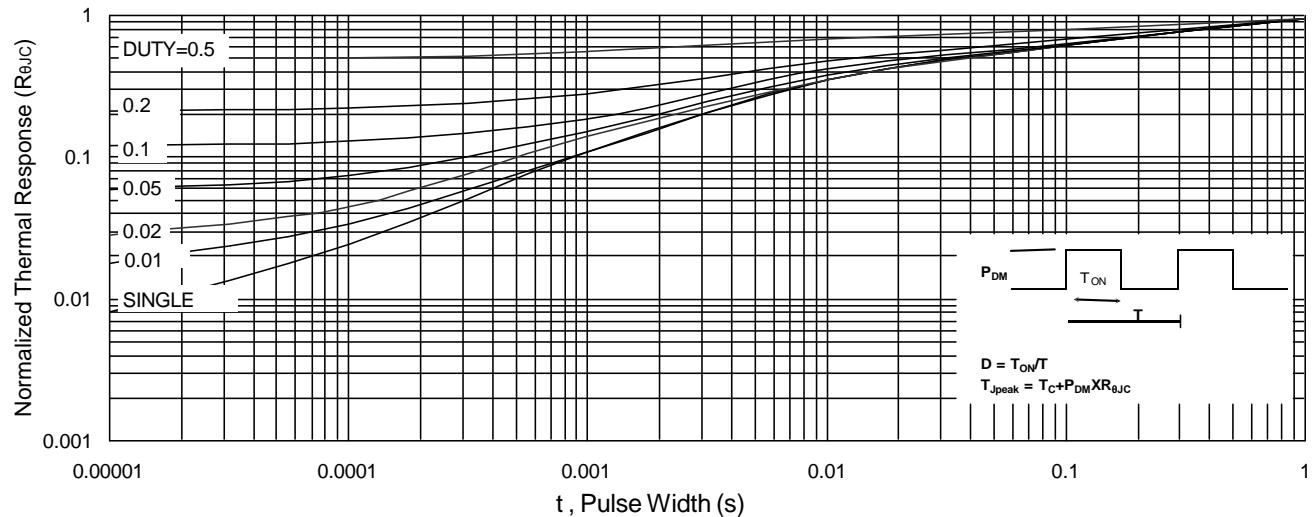
**Fig.6 Normalized R<sub>D</sub>(<sub>S</sub>) vs. T<sub>J</sub>**



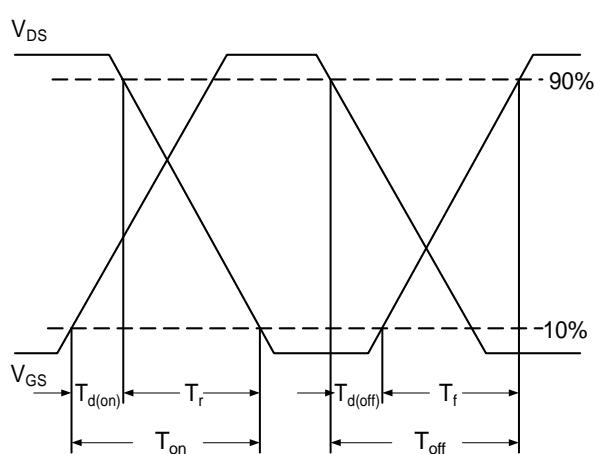
**Fig.7 Capacitance**



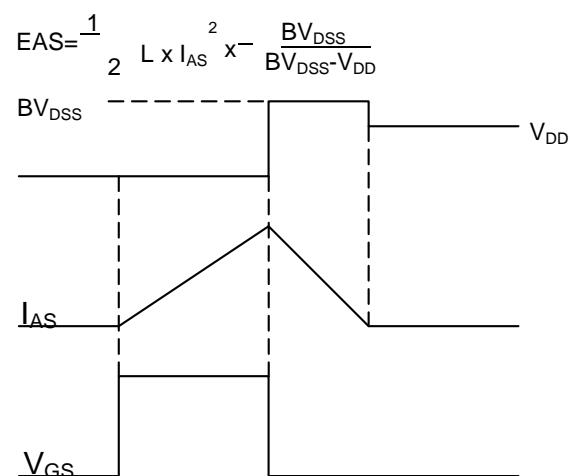
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**